Surface Mount Schottky Power Rectifier

Plastic SOD-123 Package

metal-to-silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are ac/dc and dc-dc converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical. These state-of-the-art devices have the following features:

- Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL94, V0 at 1/8"
- Package Designed for Optimal Automated Board Assembly
- ESD Ratings: Machine Model, C Human Body Model, 3B

Mechanical Characteristics

• Reel Options: MBR120LSFT1 = 3,000 per 7" reel/8 mm tape MBR120LSFT3 = 10,000 per 13" reel/8 mm tape

• Device Marking: L2L

• Polarity Designator: Cathode Band

• Weight: 11.7 mg (approximately)

• Case: Epoxy, Molded

• Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable

• Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



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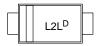
http://onsemi.com

SCHOTTKY BARRIER
RECTIFIER
1.0 AMPERES
20 VOLTS



SOD-123FL CASE 498 PLASTIC

DEVICE MARKING



L2L = Specific Device Code D = Date Code

ORDERING INFORMATION

Device	Package	Shipping	
MBR120LSFT1	SOD-123FL	3000/Tape & Reel	
MBR120LSFT3	SOD-123FL	10,000/Tape & Reel	

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	V
Average Rectified Forward Current (At Rated V _R , T _L = 115°C)	I _O	1.0	А
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 100 kHz, T _L = 110°C)	I _{FRM}	2.0	А
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	I _{FSM}	50	А
Storage Temperature	T _{stg}	-55 to 150	°C
Operating Junction Temperature	TJ	-55 to 125	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs

THERMAL CHARACTERISTICS

Thermal Resistance – Junction–to–Lead (Note 1)	R _{til}	26	°C/W	
Thermal Resistance – Junction–to–Lead (Note 2)	R _{til}	21		
Thermal Resistance – Junction–to–Ambient (Note 1)	R_{tja}	325		
Thermal Resistance – Junction–to–Ambient (Note 2)	R _{tja}	82		

^{1.} Mounted with minimum recommended pad size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3), See Figure 2	V _F	$T_J = 25^{\circ}C$	T _J = 85°C	V	l
$(I_F = 0.1 \text{ A})$ $(I_F = 1.0 \text{ A})$ $(I_F = 3.0 \text{ A})$		0.34 0.45 0.65	0.26 0.415 0.67		
Maximum Instantaneous Reverse Current (Note 3), See Figure 4	I _R	$T_J = 25^{\circ}C$	T _J = 85°C	mA	l
$(V_R = 20 \text{ V})$ $(V_R = 10 \text{ V})$		0.40 0.10	25 18		

^{3.} Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2%.

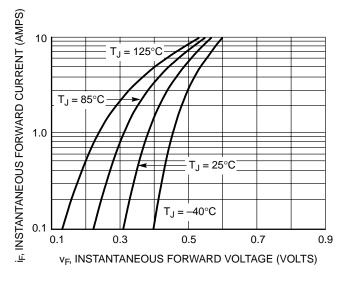


Figure 1. Typical Forward Voltage

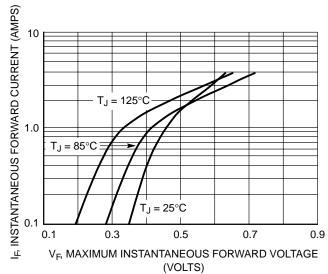


Figure 2. Maximum Forward Voltage

^{2.} Mounted with 1 in. copper pad (Cu area 700 mm²).

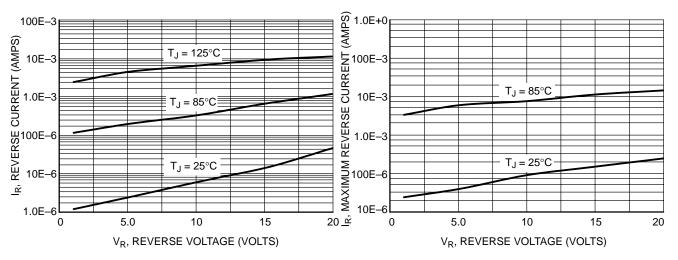


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

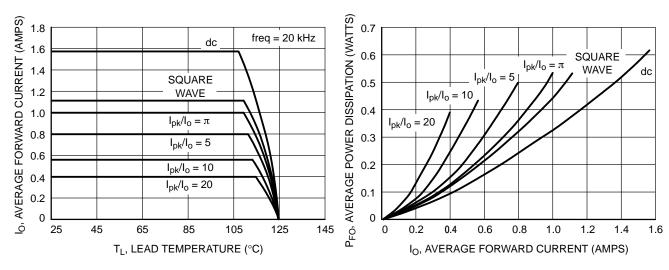


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

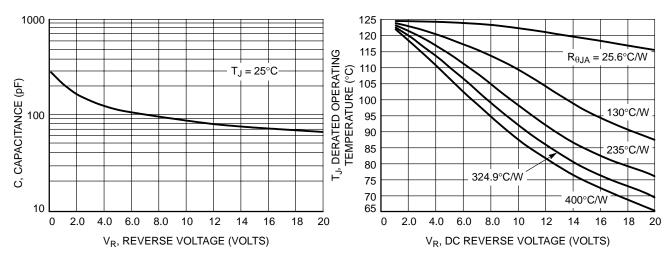


Figure 7. Capacitance

Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

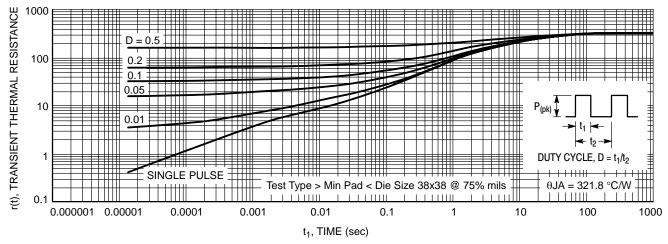
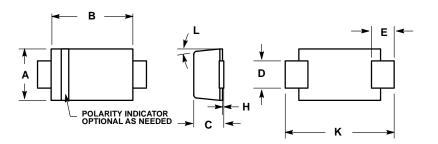
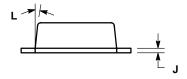


Figure 9. Thermal Response

PACKAGE DIMENSIONS

SOD-123LF CASE 498-01 ISSUE O

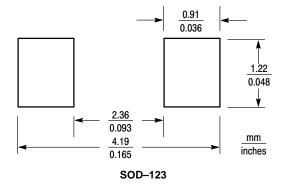




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
 4. DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.80	0.059	0.071	
В	2.50	2.90	0.098	0.114	
C	0.90	1.00	0.035	0.039	
D	0.70	1.10	0.028	0.043	
E	0.55	0.95	0.022	0.037	
Н	0.00	0.10	0.000	0.004	
J	0.10	0.20	0.004	0.008	
K	3.40	3.80	0.134	0.150	
L	0°	8 °	0°	8 °	

RECOMMENDED FOOTPRINT FOR SOD-123FL





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